PCN Number:	20140411001	**PCN Date:**	04/14/2014
Title:	Qualification of TI Taiwan as Alternate Assembly/Test site for the TPS54526PWP		
Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services
Proposed 1st Ship Date:	07/14/2014	**Estimated Sample Availability:**	04/15/2014		

Change Type:

☒	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☒	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

TI Taiwan is being qualified as an additional Assembly/Test site for the TPS54526PWP. There are no BOM differences between devices assembled at Amkor Philippines versus the current Assembly site.

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site		
TI Malaysia	Assembly Site Origin (22L)	ASO: MLA
TI Taiwan	Assembly Site Origin (22L)	ASO: TAI

Sample product shipping label (not actual product label)

Topside Device marking:
Assembly site code for TI Malaysia= K
Assembly site code for TAI= T

Product Affected	
TPS54526PWP	TPS54526PWPR

Reference Qualification Data: Approved March, 2014

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device: TPS54526PWP (MSL2-260C)

Package Construction Details

Assembly Site:	TI Taiwan	Mold Compound:	4205443
# Pins-Designator, Family:	14-PWP, TSSOP	Mount Compound:	4208458
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.98 Mil Dia., Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail
Ball Bond Shear	76 balls, 3 units min	Pass
Bond Pull	76 balls, 3 units min	Pass

Qualification Data – Approved February, 2008

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Reference Qualification #1: TAS5162DDV (MSL 3-260C)

Package Construction Details

Assembly Site:	TI Taiwan	Mold Compound:	4205443
# Pins-Designator, Family:	44-DDV, TSSOP	Mount Compound:	4206201
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.98mil, Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
**HTOL	155C (240 Hrs)	116/0	116/0	116/0
ELFR	155C (24 Hrs)	800/0	800/0	800/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Autoclave	121C (96hrs) (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
High Temp Storage Bake	170C (420 Hrs)	77/0	77/0	77/0

Notes **- Preconditioning sequence: Level 3-260C.

Qualification Data – Approved December, 2012

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Reference Qualification# 2 : BUF11704AIPWPR (MSL 2-260C)

Package Construction Details

Assembly Site:	TI- Taiwan	Mold Compound:	4205443
# Pins-Designator, Family:	28-PWP, TSSOP	Mount Compound:	4208458
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.95 Mil Dia., Au

Qualification: ☐ Plan ☒ Test Results		
Reliability Test	Conditions	Sample Size/Fail
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0
**High Temp Storage Bake	170C (420hrs)	77/0
**Autoclave	121C (96hrs)	77/0
Bond Pull	76 Wire, 3 units min	Pass
Ball Bond Shear	76 balls, 5 units min	Pass
Die Shear	(per mfg. Site specification)	Pass
Notes **- Preconditioning sequence: Level 2-260C.		

Qualification Data – Approved December, 2012

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Reference Qualification# 3 : THS6184PWP (MSL 2-260C)

Package Construction Details

Assembly Site:	TI- Taiwan	Mold Compound:	4205443
# Pins-Designator, Family:	20-PWP, TSSOP	Mount Compound:	4208458
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.95 Mil Dia., Au

Qualification: ☐ Plan ☒ Test Results		
Reliability Test	Conditions	Sample Size/Fail
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0
**High Temp Storage Bake	170C (420hrs)	77/0
**Autoclave	121C (96hrs)	77/0
Bond Pull	76 Wire, 3 units min	Pass
Ball Bond Shear	76 balls, 5 units min	Pass
Die Shear	(per mfg. Site specification)	Pass
Notes **- Preconditioning sequence: Level 2-260C.		

Qualification Data – Approved December, 2012

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Reference Qualification# 4 : TLS2283ADCAR (MSL 3-260C)

Package Construction Details

Assembly Site:	TI- Taiwan	Mold Compound:	4205443
# Pins-Designator, Family:	56-DCA, TSSOP	Mount Compound:	4208458
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.95 Mil Dia., Au

Qualification: ☐ Plan ☒ Test Results		
Reliability Test	Conditions	Sample Size/Fail
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0
**High Temp Storage Bake	170C (420hrs)	77/0
**Autoclave	121C (96hrs)	77/0
Bond Pull	76 Wire, 3 units min	Pass
Ball Bond Shear	76 balls, 5 units min	Pass
Die Shear	(per mfg. Site specification)	Pass
Notes **- Preconditioning sequence: Level 3-260C.		

Qualification Data – Approved December, 2009			
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.			
Reference Qualification# 5: TPA6030A4PWP (MSL 4-260C)			
Package Construction Details			
Assembly Site:	TI- Taiwan	Mold Compound:	4205443
# Pins-Designator, Family:	28-PWP, TSSOP	Mount Compound:	4206201
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu
Qualification: ☐ **Plan** ☒ **Test Results**			
Reliability Test	Conditions		Sample Size/Fail
**T/C -65C/150C	-65C/+150C (500 Cyc)		77/0
**High Temp Storage Bake	170C (420hrs)		77/0
**Thermal Shock	-65C/+150C (500 Cyc)		77/0
**Autoclave	121C (96hrs)		77/0
Notes **- Preconditioning sequence: Level 4-260C.			

Qualification Data – Approved February, 2011			
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.			
Reference Qualification# 6: TLS2602RDCA (MSL 3-260C)			
Package Construction Details			
Assembly Site:	TI- Taiwan	Mold Compound:	4205443
# Pins-Designator, Family:	56-DCA, TSSOP	Mount Compound:	4208458
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia., Cu
Qualification: ☐ **Plan** ☒ **Test Results**			
Reliability Test	Conditions		Sample Size/Fail
**T/C -65C/150C	-65C/+150C (500 Cyc)		77/0
**Autoclave	121C (96hrs)		77/0
Notes **- Preconditioning sequence: Level 3-260C.			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com